

Connector for Memory Stick Micro™

SCNA Series



Minimal mounting area for compact devices.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™



Combine Type

For W-SIM

Typical Specifications

Items		Specifications
Structure	Applicable media	Memory Stick Micro™
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type
Performance	Operating temperature range	-40°C to +70°C
	Voltage proof	250V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	12,000cycles

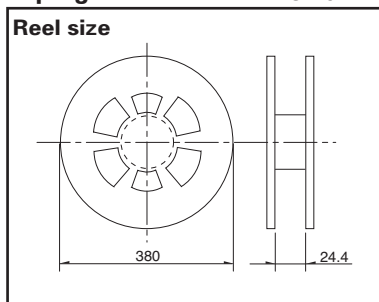
Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	0	Taping	SCNA1A0300

Packing Specifications

Taping

Unit:mm



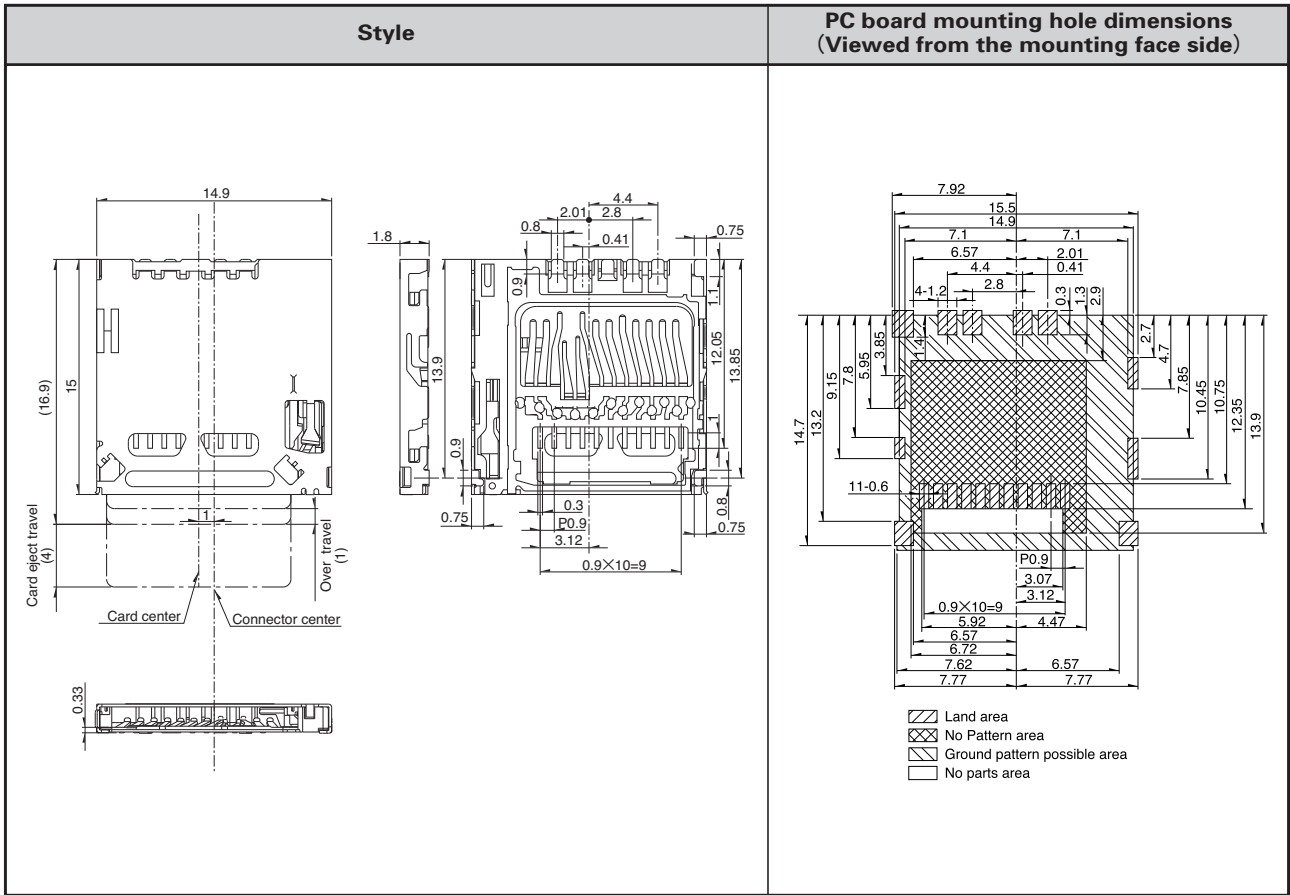
Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
1 reel	1 case /Japan	1 case /export packing		
1,500	4,500	9,000	24	403 × 403 × 249

Note

Please place purchase orders per minimum order unit N (integer).

Dimensions

Unit:mm



For SD Memory Card

For microSD™ Card


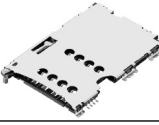

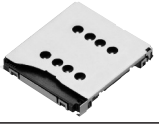
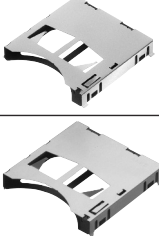
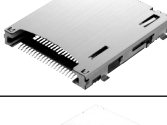
For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM

List of Varieties

Applicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
SIM Card 8pins	SCGC1B0101			Standard mount	With switch		○	541
	SCGC1B0301				With Automatic Locking Cam			
Memory Stick Micro™	SCNA1A0300				Without boss			543
Combine Type	SD Memory Card Multi-Media Card™ Memory Stick™	SCDB3A0202	Push-push type		With boss	0		545
		SCDB4A0101		Reverse mount				
	SD Memory Card Multi-Media Card™ Multi-Media Card Plus™ Memory Stick™ xD-Picture Card™	SCDG1A0101		Standard mount	547			
	SCDG2A0101	Reverse mount						
	SD Memory Card Multi-Media Card™ Memory Stick™ xD-Picture Card™	SCDG4B0100			Thin with a Thickness of 4.2mm			549
	microSD™ Card SIM Card 8pins	SCHG1B0100			Push-push type Manual insertion/removal			microSD™ Card right insertion type
W-SIM	SCZA1A0100		Push-push type	Standard mount	Without boss L type			553
	SCZA1A0200				With boss L type			
	SCZA1A0300				Without boss 0.6mm type			
	SCZA1A0400				With boss 0.6mm type			
	SCZA1A0500				Without boss 1.2mm type			
	SCZA1A0600				With boss 1.2mm type			
	SCZA2A0100		Manual insertion/removal	With boss L type				
	SCZA2A0200			Without boss 0.6mm type				

For SD Memory Card
 For microSD™ Card
 For SIM Card 8pins
 For Memory Stick Micro™
 Combine Type
 For W-SIM

Note

○marks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

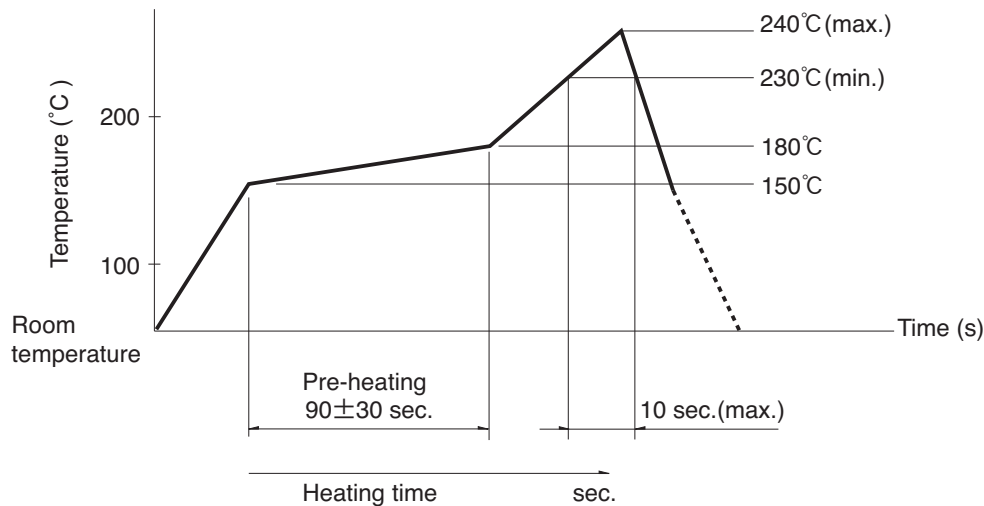
Note

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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

1.Connector handling precautions

- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.

If you wash it, it may cause deterioration of mechanically and electrically.

If washing is necessary, please make contact with us beforehand.

2. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3. When soldering, do not use water soluble flux because this may corrode the product.

4. regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5. As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6. Please do not solder at the ejector pushing position.

7. To prevent contact disturbance by the sulfuration or oxidation of the contact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.

- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorine gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.

8. Don't push or hold down the metal cover of the connector, otherwise there is a possibility that the card would not be ejected or influences to other function.

9. Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.

- Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- Establish CR accumulation circuit.

10. This product does not operate normally when the card which does not conform to the specification is used occasionally.

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